

ST-98-003B



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1732
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February 22, 2002

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

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Subject:

Serial No. 10/043,603 01/14/02

J. Briar

MOLDED STIFFENER FOR FLEXIBLE
CIRCUIT MOLDING

Grp. Art Unit: 1732

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INFORMATION DISCLOSURE STATEMENT

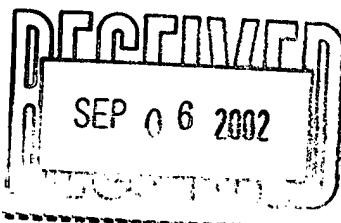
Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner of Patents and
Trademarks, Washington, D.C. 20231, on February 27, 2002.

Stephen B. Ackerman, Reg.# 37761



Signature/Date

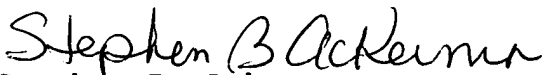
Stephen B. Ackerman 2/27/02

U.S. Patent 5,506,756 to Haley, "Tape BGA Package Die-Up/Die Down", describes a ball grid array package containing an integrated circuit die that is directly mounted to either a heat sink or a printed circuit board.

U.S. Patent 5,241,133 to Mullen, III et al., "Leadless Pad Array Chip Carrier", describes a leadless pad array chip carrier package. A semiconductor device is electrically wire bonded and attached with conductive adhesive to a metallized pattern on a printed circuit board.

U.S. Patent 5,635,671 to Freyman et al., "Mold Runner Removal from a Substrate-Based Packaged Electronic Device", describes encapsulation of an electronic device using injection molding with a two piece mold using a degating region having a material chosen such that the material in the degating region forms a weak bond with the encapsulant used.

Sincerely,


Stephen B. Ackerman,
Reg. No. 37761